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## (54) NON-VOLATILE MEMORY DEVICE FOR STORING WRITE DATA HAVING DIFFERENT LOGIC LEVELS

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G11C 16/10 (2006.01)

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CPC .. G06F 3/0629; G06F 3/0656; G06F 13/1673 USPC ....... 711/154, 156, 167; 710/52, 310; 712/225, 248

See application file for complete search history.

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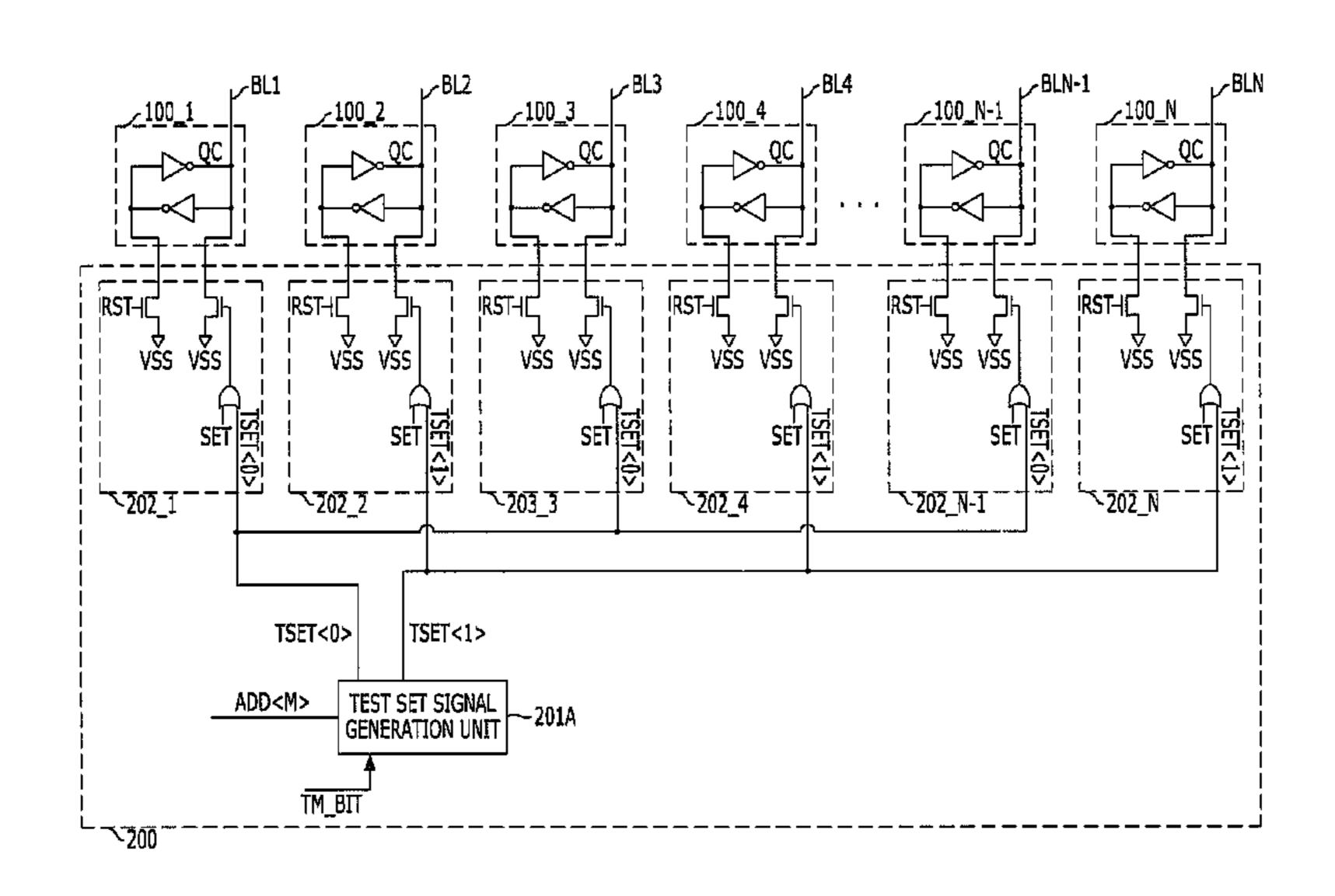
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### (57) ABSTRACT

A non-volatile memory device includes a plurality of bit lines; a plurality of page buffers corresponding to the bit lines, respectively, and configured to each store a write data; and a control circuit configured to control at least one page buffer of the plurality of page buffers to store the write data of a first logic level and control other ones of the plurality of page buffers to store the write data of a second logic level, wherein the control circuit is further configured to select the at least one page buffer based on an address inputted to the control circuit. Since write data of diverse patterns may be generated within a non-volatile memory device by using a portion of the bits of the address, a test operation of the non-volatile memory device may be performed within a short time.

#### 8 Claims, 4 Drawing Sheets



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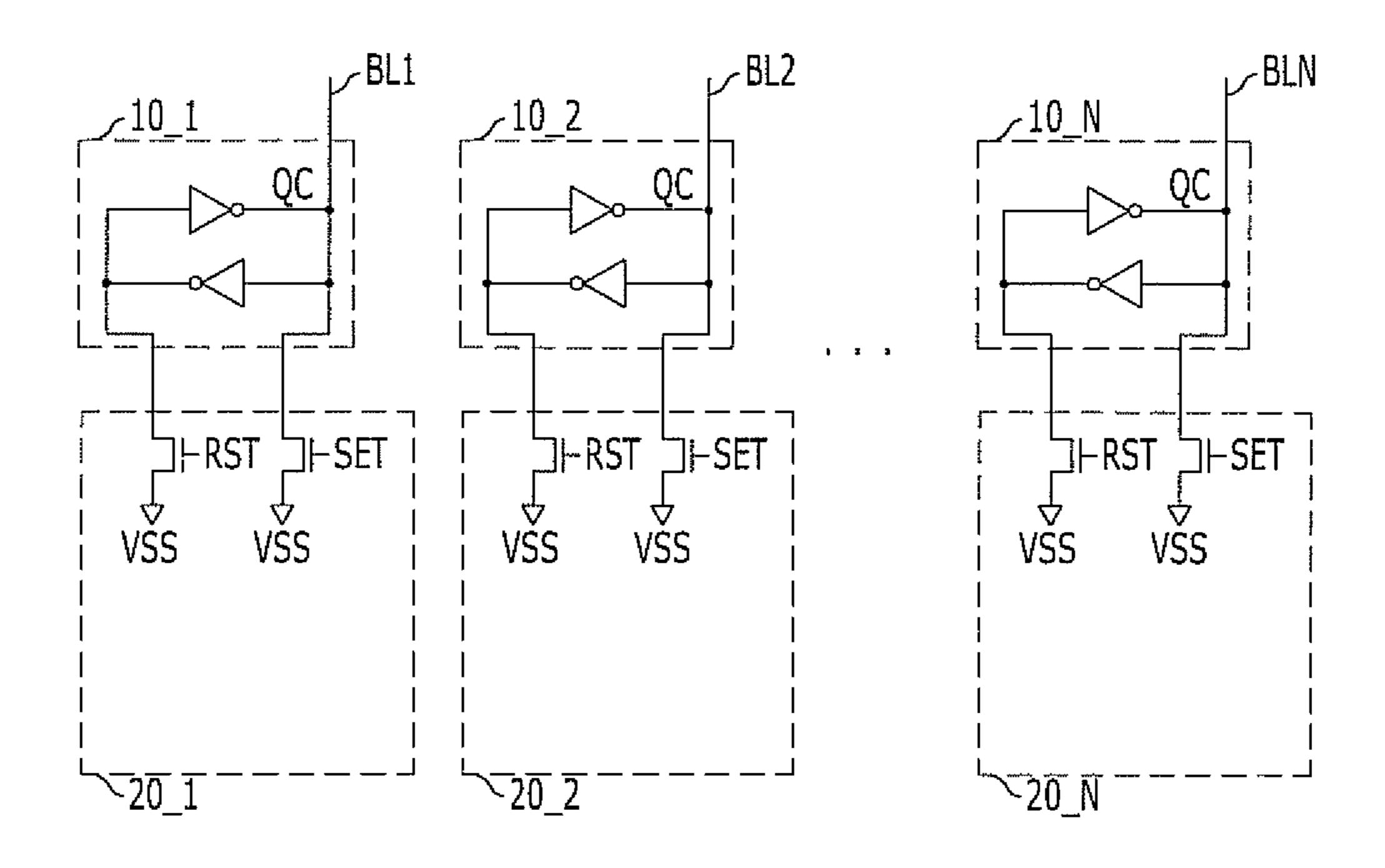
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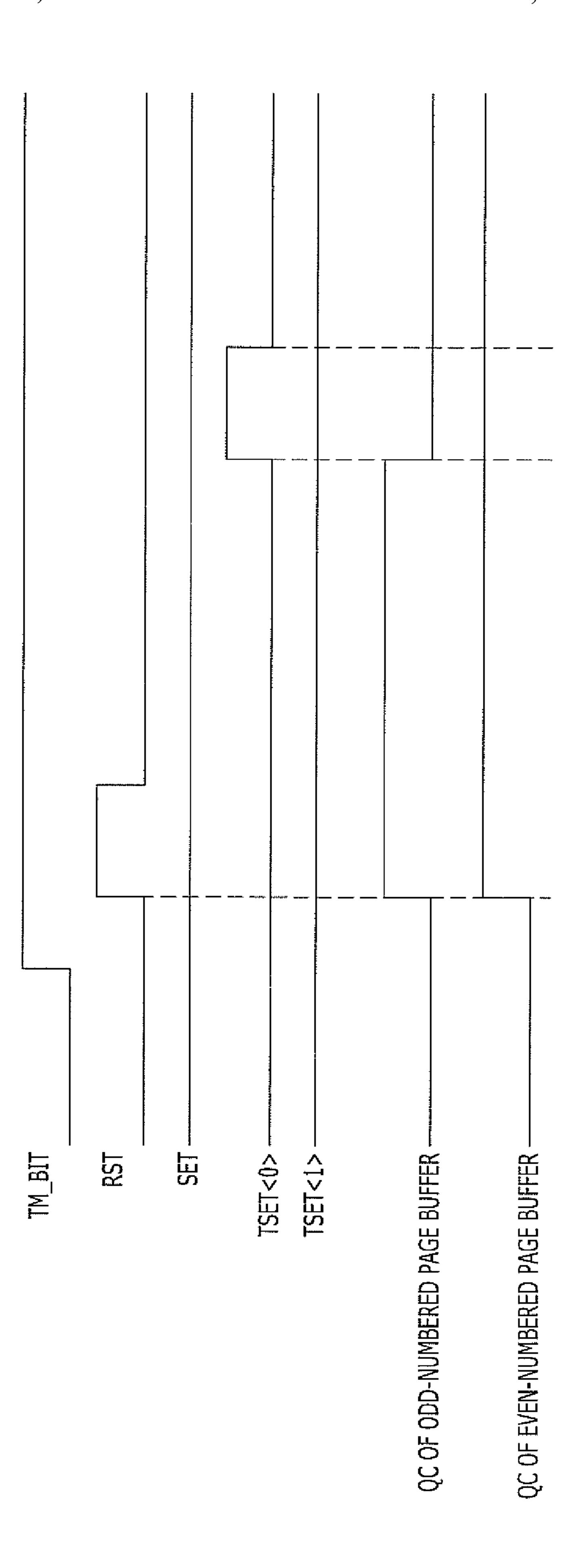
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FIG. 1 (PRIOR ART)



TSET<1>] SET \_100\_N\_ SS. TSET<0> SÉT 100 N-1 TSET<1> SET 잉 ~tr.¦ 100 TSET<0> SET 100 TEST SET SIGNAL
GENERATION UNIT TSET<1> BL2 TSET<1> SEI E E TSET<0> <u>|</u>≥ RS1 TSET<0> SET

FIG.



TSET<3> SET 100 N BLN-1 TSET<2> SET = 25 BLN-2 TSET<1> 100 N-2 TSET<0> 100 N-3 <u>B</u>.4 TSET<3> 紀-4, 4 100 TSET<3> BE3 TSET<2> SET 001 TEST SET SIGNAL
GENERATION UNIT **BL2** TSET TSET<1> SET 100\_2 H IRST-I <u>| TSET<0></u> SE 1007

## NON-VOLATILE MEMORY DEVICE FOR STORING WRITE DATA HAVING DIFFERENT LOGIC LEVELS

## CROSS-REFERENCE TO RELATED APPLICATIONS

The present application claims priority of Korean Patent Application No. 10-2011-0140501, filed on Dec. 22, 2011, which is incorporated herein by reference in its entirety.

#### BACKGROUND

#### 1. Field

Exemplary embodiments of the present invention relate to 15 a non-volatile memory device.

#### 2. Description of the Related Art

As the integration degree of a non-volatile memory device, such as a flash memory device, increases, additional costs and time are spent in testing a non-volatile memory device.

An exemplary operation of programming a test data in a memory cell (not shown) during a test operation of a non-volatile memory device is performed as follows. For illustration purposes, it is assumed that a non-volatile memory device includes N page buffers and N bit lines.

Each of the N page buffers receives and stores a test data that is inputted from an external device. The test data stored in the respective N page buffers are loaded onto N bit lines, respectively, and programmed in N memory cells that are coupled with the N bit lines. When a test operation is performed in the general program operation, the test data is inputted from an external device and thus, the test operation takes additional time.

To reduce the test time, the process of receiving a test data from an external device may be obviated, by generating a test 35 data internally and storing the test data in a page buffer. This method will be described in detail with reference to FIG. 1.

FIG. 1 illustrates a conventional non-volatile memory device. The non-volatile memory device may include N bit lines BL1 to BLN, N page buffers 10\_1 to 10\_N, and N data 40 controllers 20\_1 to 20\_N.

Each of the N page buffers 10\_1 to 10\_N stores a write data, which means a data to be programmed in a memory cell (not shown).

Each of the N data controllers 20\_1 to 20\_N corresponds to 45 device. the N page buffers 10\_1 to 10\_N, respectively. When a reset signal RST is activated, each of the N data controllers 20\_1 to 20\_N controls the corresponding page buffer to store the write data of a logic high level. When a set signal SET is activated, each of the N data controllers 20\_1 to 20\_N controls the corresponding page buffer to store the write data of a logic low level.

EIG. device.

FIG. device.

During the test operation of the non-volatile memory device illustrated in FIG. 1, an operation of generating write data of a pattern and programming the write data in memory 55 cells (not shown) is performed as follows.

The reset signal RST is enabled to a logic high level in the initial duration of the test operation. Each of the N data controllers 20\_1 to 20\_N controls the corresponding page buffer to store the write data of a logic high level in response 60 to the reset signal RST of a logic high level. As a result, a high level write data is loaded on the latch node QC of each of the N page buffers 10\_1 to 10\_N. The write data loaded on the latch node QC of each of the N page buffers 10\_1 to 10\_N is applied to a memory cell (not shown) through a bit line. 65 According to an example, a data of '1111111111...' is programmed in N memory cells (not shown).

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Meanwhile, when the set signal SET is enabled to a logic high level in the initial duration of the test operation, a write data of a logic low level is loaded on the latch node QC of each of the N page buffers 10\_1 to 10\_N. According to an example, a data of '00000000. . . 'is programmed in N memory cells (not shown).

However, when the test operation is performed as described above, the pattern of the test data that are programmed in memory cells (not shown) is limited to '111111111...' or '000000000...'.

#### **SUMMARY**

An embodiment of the present invention is directed to a non-volatile memory device that may internally generate test data of diverse patterns.

In accordance with an embodiment of the present invention, a non-volatile memory device includes: a plurality of bit lines; a plurality of page buffers corresponding to the bit lines, respectively, and configured to each store a write data; and a control circuit configured to control at least one page buffer of the plurality of page buffers to store the write data of a first logic level and control other ones of the plurality of page buffers to store the write data of a second logic level, wherein the control circuit is further configured to select the at least one page buffer based on an address inputted to the control circuit.

In accordance with another embodiment of the present invention, a non-volatile memory device includes: a plurality of bit lines; a plurality of page buffers corresponding to the plurality of bit lines, respectively, and configured to each store a write data; and a control circuit configured to control at least one page buffer of the plurality of page buffers to store the write data of a first logic level and control other ones of the plurality of page buffers to store the write data of a second logic level, wherein the control circuit is further configured to select the at least one page buffer based on a portion of bits of an address consisting of multiple bits.

## BRIEF DESCRIPTION OF THE DRAWINGS

- FIG. 1 illustrates a conventional non-volatile memory device.
- FIG. 2 illustrates a non-volatile memory device in accordance with an embodiment of the present invention.
- FIG. 3 is a timing diagram illustrating an operation of generating write data and programming the write data in memory cells during a test operation of the non-volatile memory device shown in FIG. 2.
- FIG. 4 illustrates a non-volatile memory device in accordance with another embodiment of the present invention.

## DETAILED DESCRIPTION

Exemplary embodiments of the present invention will be described below in more detail with reference to the accompanying drawings. The present invention may, however, be embodied in different forms and should not be construed as limited to the embodiments set forth herein. Rather, these embodiments are provided so that this disclosure will be thorough and complete, and will fully convey the scope of the present invention to those skilled in the art. Throughout the disclosure, like reference numerals refer to like parts throughout the various figures and embodiments of the present invention.

FIG. 2 illustrates a non-volatile memory device in accordance with an embodiment of the present invention.

The non-volatile memory device may include N bit lines BL1 to BLN, N page buffers 100\_1 to 100\_N, and a control circuit 200.

Each of the N bit lines BL1 to BLN is coupled with a memory cell (not shown). The write data respectively loaded on the N bit lines BL1 to BLN are programmed in respective memory cells (not shown).

The N page buffers 100\_1 to 100\_N correspond to the N bit lines BL1 to BLN, respectively, and store write data. During a program operation, each of the N page buffers 100\_1 to 100\_N transfers a write data to a bit line coupled to itself.

The control circuit 200 controls page buffers selected based on some address bits (for example, ADD<M>) of an address ADD<1:M> to store a write data of a first logic level among the N page buffers 100\_1 to 100\_N and controls the other page buffers to store a write data of a second logic level. The write data of the first logic level may be a data of a logic low level, and the write data of the second logic level may be a data of a logic high level. Alternatively, the write data of the first logic level may be a data of a logic high level, and the write data of the second logic level may be a data of a logic 25 low level. The number of page buffers selected by the address bit ADD<M> of the address ADD<1:M> is at least one. For illustration purposes, FIG. 2 shows a case where the control circuit 200 selects odd-numbered page buffers 100\_2K-1, 30 where  $1 \le K \le N/2$ , or even-numbered page buffers  $100_2K$ among the N page buffers 100\_1 to 100\_N based on an M<sup>th</sup> address bit ADD<M>. To be specific, the control circuit 200 may be designed to select odd-numbered page buffers 100\_2K-1, where 1≤K≤N/2, and store data of a logic low level in the selected odd-numbered page buffers 100\_2K-1, where  $1 \le K \le N/2$ , and store data of a logic high level in the even-numbered page buffers 100\_2K, when the M<sup>th</sup> address bit ADD<M> of the address ADD<1:M> is in a logic high 40 level. Alternatively, the control circuit 200 may be designed to select even-numbered page buffers 100\_2K, where 1≤K≤N/ 2, and store data of a logic low level in the selected evennumbered page buffers  $100_2K$ , where  $1 \le K \le N/2$ , and store data of a logic high level in the odd-numbered page buffers  $100_2K-1$ , when the M<sup>th</sup> address bit ADD<M> of the address ADD<1:M> is in a logic low level.

The control circuit 200 may include a test set signal generation unit 201A and N data control units 202\_1 to 202\_N.

The test set signal generation unit **201**A generates first and second test set signals TSET<0:1>, and when a test signal TM\_BIT is enabled, the test set signal generation unit 201A decodes the  $M^{th}$  address bit ADD<M> of the address ADD<1: M> to enable any one between the first test set signal TSET<0> and the second test set signal TSET<1>. Here, the test signal TM\_BIT is a signal representing a test mode or a normal mode. To be specific, when the test signal TM\_BIT is in a logic high level, the test signal TM\_BIT may represent a 60 test mode. When the test signal TM\_BIT is in a logic low level, the test signal TM\_BIT may represent a normal mode. The test set signal generation unit 201A may be designed to decode the  $M^{th}$  address bit ADD<M> of the address ADD<1: M> and generate the first and second test set signals TSET<0: 65 1> as shown in Table 1 in the test mode, where the test signal TM\_BIT is in a logic high level in the test mode.

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TABLE 1

-	and second test set sign by decoding one addre	
ADD <m></m>	TSET<0>	TSET<1>
0 1	0 1	1 O

When the M<sup>th</sup> address bit ADD<M> of the address ADD<1:M> is in a logic high level in the test mode, where the test mode is indicated by the test signal TM\_BIT being in a logic high level, the test set signal generation unit 201A may be designed to generate the first test set signal TSET<0> of a logic high level and the second test set signal TSET<1> of a logic low level. Also, when the M<sup>th</sup> address bit ADD<M> of the address ADD<1:M> is in a logic low level in the test mode, the test set signal generation unit 201A may be designed to generate the first test set signal TSET<0> of a logic low level and the second test set signal TSET<1> of a logic high level.

Meanwhile, the test set signal generation unit **201**A may be designed to perform the operation to generate and enable the first and second test set signals TSET<0:1> as shown in Table 1 in the test mode. Further, the test set signal generation unit **201**A may be designed to generate the first and second test set signals TSET<0:1> of a logic low level in the normal mode, which is indicated by the test signal TM\_BIT being in a logic low level.

The N data control units 202\_1 to 202\_N correspond to the N page buffers 100\_1 to 100\_N, respectively, and control the level of the write data stored in the corresponding N page buffers 100\_1 to 100\_N. To be specific, when a reset signal RST is enabled, each of the N data control units 202\_1 to 202\_N controls a corresponding page buffer to store the write data of the second logic level in the corresponding page buffer, and when the test set signal inputted to the data control unit is enabled among the first and second test set signals TSET<0:1>, the data control unit performs a control operation to store the write data of the first logic level in the corresponding page buffer. For example, when the reset signal RST is enabled, the odd-numbered data control units 202\_2K-1 control respective odd-numbered pages buffers 100\_2K-1, where 1≤K≤N/2 to store the write data of a logic 45 high level in the odd-numbered page buffers 100\_2K-1. When any one of the first test set signal TSET<0> and the set signal SET is enabled, the odd-numbered data control units 202\_2K-1 may perform a control operation to store the write data of a logic low level in the corresponding odd-numbered page buffers 100\_2K-1.

When the reset signal RST is enabled (that is, activated), the even-numbered data control units 202\_2K control the even-numbered page buffers 100\_2K to store the write data of a logic high level in the even-numbered page buffers 100\_2K, which are page buffers corresponding to the even-numbered data control units 202\_2K, where 1≤K≤N/2. When any one of the second test set signal TSET<1> and the set signal SET is enabled, the even-numbered data control units 202\_2K may control the corresponding even-numbered page buffers 100\_2K to store the write data of a logic low level in the corresponding even-numbered page buffers 100\_2K.

FIG. 3 is a timing diagram illustrating an operation of generating write data and programming the write data in memory cells during a test operation of the non-volatile memory device shown in FIG. 2.

In the test mode, the test signal TM\_BIT is in a logic high level.

The reset signal RST transitions to a logic high level in the initial duration of a test operation.

Each of the N data control units 202\_1 to 202\_N controls storage of the write data of a logic high level in the page buffer corresponding to the data control unit in response to the reset signal RST of the logic high level. Thus, write data of a logic high level are loaded on the latch nodes QC of the N page buffers 100\_1 to 100\_N.

Meanwhile, the set signal SET may be inputted in a logic low level in the test mode, which is indicated by the test signal 10 TM\_BIT being in a logic high level.

The test set signal generation unit **201**A generates the first and second test set signals TSET<0:1> and enables any one of the first test set signal TSET<0> and the second test set signal TSET<1> by decoding the M<sup>th</sup> address bit ADD<M> of the 15 address ADD<1:M>. Hereinafter, for illustration purposes, it is assumed that the test set signal generation unit **201**A is designed to generate the first and second test set signals TSET<0:1> as shown in Table 1 by decoding the M<sup>th</sup> address bit ADD<M> when the M<sup>th</sup> address bit ADD<M> is inputted 20 to the test set signal generation unit **201**A in a logic high level. In short, the test set signal generation unit **201**A generates the first test set signal TSET<0> of a logic high level and the second test set signal TSET<1> of a logic low level by decoding the M<sup>th</sup> address bit ADD<M> of a logic high level.

Here, the first test set signal TSET<0> is inputted to the odd-numbered data control units 202\_2K-1 among the N data control units 202\_1 to 202\_N, and the second test set signal TSET<1> is inputted to the even-numbered data control units 202\_2K.

The odd-numbered data control units 202\_2K-1 controls a storage of the write data of a logic low level in the corresponding page buffers, which are the odd-numbered page buffers 100\_2K-1, in response to the first test set signal TSET<0> of a logic high level. In short, the write data of a logic low level 35 are loaded on the latch nodes QC of the odd-numbered page buffers 100\_2K-1.

Meanwhile, since both the set signal SET and second test set signal TSET<1> are in the logic low level, the even-numbered data control units 202\_2K do not change the level 40 of the write data stored in the corresponding page buffers, which are the even-numbered page buffers 100\_2K. Therefore, the write data loaded on the latch node QC of the even-numbered data control units 202\_2K maintain the logic high level.

In short, the odd-numbered page buffers 100\_2K-1 store the write data of a logic low level, and the even-numbered page buffers 100\_2K store the write data of a logic high level. The write data stored in the N page buffers 100\_1 to 100\_N are transferred to the N bit lines BL1 to BLN that correspond to the N page buffers 100\_1 to 100\_N, respectively, and the write data loaded on the N bit lines BL1 to BLN are programmed in the memory cells (not shown) coupled with the N bit lines BL1 to BLN. Thus, data of '01010101. . . ' are programmed in the N memory cells (not shown).

Meanwhile, when it is assumed that the M<sup>th</sup> address bit ADD<M> of a logic low level is inputted to the test set signal generation unit 201A, the test set signal generation unit 201A generates a first test set signal TSET<0> of a logic low level and a second test set signal TSET<1> of a logic high level in 60 opposite of the signal levels shown in FIG. 3. Thus, the odd-numbered page buffers 100\_2K-1 store the write data of a logic high level, and the even-numbered page buffers 100\_2K store the write data of a logic low level, which is the opposite to the above-described operation. Thus, data of 65 '10101010...' are programmed in the N memory cells (not shown).

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FIG. 4 illustrates a non-volatile memory device in accordance with another embodiment of the present invention. The non-volatile memory device of FIG. 4 selects one page buffer among four page buffers based on two address bits ADD<M-1:M> of the address ADD<1:M> so that the level of the write data stored in the selected page buffers is different from the level of the write data stored in the other three page buffers.

The non-volatile memory device may include N bit lines BL1 to BLN, N page buffers 100\_1 to 100\_N, and a control circuit 200.

The structure and operation principle of the N bit lines BL1 to BLN are the same as the N bit lines BL1 to BLN described in FIG. 2.

The structure and operation principle of the N page buffers 100\_1 to 100\_N are the same as the N page buffers 100\_1 to 100\_N described in FIG. 2.

The control circuit **200** controls page buffers selected based on certain address bits ADD<M-1:M> of an address ADD<1:M> to store a write data of a first logic level among the N page buffers **100\_1** to **100\_N** and controls the other page buffers to store a write data of a second logic level. The control circuit **200** may include a test set signal generation unit **201**B and N data control units **203\_1** to **203\_N**.

The test set signal generation unit **201**B generates first to fourth test set signals TSET<0:3>, and in a test mode, for which a test signal TM\_BIT is in a logic high level, the test set signal generation unit **201**B decodes the two address bits ADD<M-1:M> of the address ADD<1:M> to enable any one among the first to fourth test set signals TSET<0:3>. For illustration purposes, FIG. **4** shows a case where the test set signal generation unit **201**B decodes the M-1<sup>th</sup> address bit ADD<M-1> and M<sup>th</sup> address bit ADD<M> of the address ADD<1:M>. For example, the test set signal generation unit **201**B may be designed to generate the first to fourth test set signals TSET<0:3> as shown in Table 2 by decoding the two address bits ADD<M-1:M>.

TABLE 2

	-	f first to fourth ated by decoding	•		
	ADD <m-1:m></m-1:m>	TSET<0>	TSET<1>	TSET<2>	TSET<3>
5	00	1	0	0	0
	01	0	1	0	0
	10	0	0	1	0
	11	O	O	O	1

Meanwhile, the test set signal generation unit 201B may be designed to perform an operation to generate and activate the first to fourth test set signals TSET<0:3> in the test mode, where the test signal TM\_BIT is in a logic high level. Further, the test set signal generation unit 201B may be designed to generate the first to fourth test set signals TSET<0:3> of a logic low level in the normal mode, where the test signal TM\_BIT is in a logic low level.

The N data control units 203\_1 to 203\_N correspond to the N page buffers 100\_1 to 100\_N, respectively, and control the level of the write data that are stored in the corresponding N page buffers 100\_1 to 100\_N. To be specific, when a reset signal RST is activated, each of the N data control units 203\_1 to 203\_N performs a control to store the write data of the second logic level in the corresponding page buffer, and when the test set signal inputted to the control unit is activated among the first to fourth test set signals TSET<0:3>, the data

control unit controls the corresponding page buffer to store the write data of the first logic level in the corresponding page buffer.

For example, when the reset signal RST is enabled, the  $(4P+1)^{th}$  data control unit 203\_4P+1, where  $0 \le P \le N/4$ , among the N data control units 203\_1 to 203\_N performs a control to store the write data of a second logic level in the corresponding page buffer, which is a  $(4P+1)^{th}$  page buffer  $100\_4P+1$ . When any one of the first test set signal TSET<0> and the set signal SET is enabled, the  $(4P+1)^{th}$  data control unit 203\_4P+ 10 1, where  $0 \le P \le N/4$ , may perform a control to store the write data of a first logic level in the  $(4P+1)^{th}$  page buffer  $100\_4P+1$ corresponding to the data control unit. To be specific, when the reset signal RST is in a logic high level, the  $(4P+1)^{th}$  data control unit 203\_4P+1 controls the (4P+1)<sup>th</sup> page buffer 15 100\_4P+1 to store the write data of a logic high level in the  $(4P+1)^{th}$  page buffer  $100\_4P+1$ . When any one of the first test set signal TSET<0> and the set signal SET is in a logic high level, the  $(4P+1)^{th}$  data control unit 203\_4P+1 controls the corresponding  $(4P+1)^{th}$  page buffer  $100\_4P+1$  to store the 20 write data of a logic low level in the corresponding  $(4P+1)^{th}$ page buffer **100\_4P+1**.

When the reset signal RST is enabled, the  $(4P+2)^{th}$  data control unit 203\_4P+2, where  $0 \le P \le N/4$ , among the N data control units 203\_1 to 203\_N controls a storage of the write 25 data of the second logic level in the corresponding page buffer, which is a  $(4P+2)^{th}$  page buffer  $100\_4P+2$ . When any one of the second test set signal TSET<1> and the set signal SET is enabled, the  $(4P_{\perp}2)^{th}$  data control unit 203\_4P+2, where  $0 \le P \le N/4$ , may control the corresponding  $(4P+2)^{th}$  30 page buffer 100\_4P+2 to store the write data of the first logic level in the  $(4P+2)^{th}$  page buffer  $100\_4P+2$ . The structure and operation principle of the  $(4P+2)^{th}$  data control unit 203\_4P+2 are similar to those of the (4P+1)<sup>th</sup> data control unit used instead of the first test set signal TSET<0>.

When the reset signal RST is enabled, the  $(4P+3)^{th}$  data control unit 203\_4P+3, where  $0 \le P \le N/4$ , among the N data control units 203\_1 to 203\_N controls a storage of the write data of the second logic level in the corresponding page 40 buffer, which is a  $(4P+3)^{th}$  page buffer  $100\_4P+3$ . When any one of the third test set signal TSET<2> and the set signal SET is enabled, the  $(4P+3)^{th}$  data control unit 203\_4P+3, where  $0 \le P \le N/4$ , may control a storage of the write data of the first logic level in the  $(4P+3)^{th}$  page buffer  $100\_4P_{\perp}3$  corre- 45 sponding to the data control unit. The structure and operation principle of the  $(4P+3)^{th}$  data control unit 203\_4P+3 are similar to those of the  $(4P_{\perp}1)^{th}$  data control unit  $203\_4P_{\perp}1$ , except that the third test set signal TSET<2> is used instead of the first test set signal TSET<0>.

When the reset signal RST is enabled, the (4P+4)<sup>th</sup> data control unit 203\_4P+4, where  $0 \le P \le N/4$ , among the N data control units 203\_1 to 203\_N controls a storage of the write data of the second logic level in the corresponding page buffer, which is a  $(4P+4)^{th}$  page buffer  $100\_4P+4$ . When any 55 one of the fourth test set signal TSET<3> and the set signal SET is enabled, the  $(4P+4)^{th}$  data control unit 203\_4P+4, where 0≤P<N/4, may control a storage of the write data of the first logic level in the  $(4P+4)^{th}$  page buffer  $100\_4P+4$  corresponding to the data control unit. The structure and operation 60 principle of the  $(4P+4)^{th}$  data control unit  $203_4P+4$  are similar to those of the  $(4P+1)^{th}$  data control unit  $203\_4P+1$ , except that the fourth test set signal TSET<3> is used instead of the first test set signal TSET<0>.

For example, when the control circuit **200** includes 16 data 65 control units **203**\_**1** to **203**\_**16**, 16 data control units **203**\_**1** to 203\_16 may be designed as follows. When the reset signal

RST is in a logic high level, the first, fifth, ninth and 13<sup>th</sup> data control units 203\_1, 203\_5, 203\_9 and 203\_13 controls a storage of the write data of a logic high level in the first, fifth, ninth and 13<sup>th</sup> page buffers 100\_1, 100\_5, 100\_9 and 100\_13 that correspond to the first, fifth, ninth and 13<sup>th</sup> data control units 203\_1, 203\_5, 203\_9 and 203\_13, respectively. When any one of the set signal SET and the first test set signal TSET<0> is in a logic high level, the first, fifth, ninth and 13<sup>th</sup> data control units 203\_1, 203\_5, 203\_9 and 203\_13 may control the first, fifth, ninth and  $13^{th}$  page buffers  $100_{-}1$ , 100\_5, 100\_9 and 100\_13 to store the write data of a logic low level in the first, fifth, ninth and  $13^{th}$  page buffers  $100_{-}1$ , 100 5, 100 9 and 100 13.

When the reset signal RST is in a logic high level, the second, sixth, tenth and  $14^{th}$  data control units 203\_2, 203\_6, 203\_10 and 203\_14 perform a control operation to store the write data of a logic high level in the second, sixth, tenth and 14<sup>th</sup> page buffers 100\_2, 100\_6, 100\_10 and 100\_14 that correspond to the second, sixth, tenth and 14<sup>th</sup> data control units 203\_2, 203\_6, 203\_10 and 203\_14, respectively. When any one of the set signal SET and the second test set signal TSET<1> is in a logic high level, the second, sixth, tenth and 14<sup>th</sup> data control units 203\_2, 203\_6, 203\_10 and 203\_14 may perform a control operation to store the write data of a logic low level in the second, sixth, tenth and 14<sup>th</sup> page buffers 100\_2, 100\_6, 100\_10 and 100\_14.

Also, when the reset signal RST is in a logic high level, the third, seventh,  $11^{th}$  and  $15^{th}$  data control units 203\_3, 203\_7, 203\_11 and 203\_15 perform a control operation to store the write data of a logic high level in the third, seventh, 11<sup>th</sup> and 15<sup>th</sup> page buffers 100\_3, 100\_7, 100\_11 and 100\_15 that correspond to the third, seventh,  $11^{th}$  and  $15^{th}$  data control units 203\_3, 203\_7, 203\_11 and 203\_15, respectively. When any one of the set signal SET and the third test set signal 203\_4P+1, except that the second test set signal TSET<1> is 35 TSET<2> is in a logic high level, the third, seventh, 11<sup>th</sup> and 15<sup>th</sup> data control units 203\_3, 203\_7, 203\_11 and 203\_15 may perform a control operation to store the write data of a logic low level in the third, seventh,  $11^{th}$  and  $15^{th}$  page buffers 100\_3, 100\_7, 100\_11 and 100\_15.

> When the reset signal RST is in a logic high level, the fourth, eighth,  $12^{th}$  and  $16^{th}$  data control units **203\_4**, **203\_8**, 203\_12 and 203\_16 perform a control operation to store the write data of a logic high level in the fourth, eighth, 12<sup>th</sup> and 16<sup>th</sup> page buffers 100\_4, 100\_8, 100\_12 and 100\_16 that correspond to the fourth, eighth,  $12^{th}$  and  $16^{th}$  data control units 203\_4, 203\_8, 203\_12 and 203\_16, respectively. When any one of the set signal SET and the fourth test set signal TSET<3> is in a logic high level, the fourth, eighth,  $12^{th}$  and 16<sup>th</sup> data control units 203\_4, 203\_8, 203\_12 and 203\_16 50 may perform a control to store the write data of a logic low level in the fourth, eighth,  $12^{th}$  and  $16^{th}$  page buffers 100\_4, 100\_8, 100\_12 and 100\_16.

Since the operation of generating the write data and programming the generated write data in memory cells (not shown) during a test operation of a non-volatile memory device shown in FIG. 4 is similar to that of FIG. 3, the operation is described with reference to FIG. 3. For illustration purposes, it is assumed that the test set signal generation unit **201**B generates the first to fourth test set signals TSET<0: 3> as shown in Table 2 by decoding two address bits ADD < M-1:M>.

In the test mode, the test signal TM\_BIT is in a logic high level.

The reset signal RST is enabled to a logic high level in the initial duration of a test operation.

Each of the N data control units 203\_1 to 203\_N performs a control operation to store the write data of a logic high level

10 TABLE 3

in the page buffer corresponding to the data control unit in response to the reset signal RST of the logic high level. After all, write data of a logic high level are loaded on the latch nodes QC of the N page buffers 100\_1 to 100\_N.

Meanwhile, the set signal SET may be inputted in a logic low level in the test mode, which means that the test signal TM\_BIT is in a logic high level.

The test set signal generation unit **201**B generates the first to fourth test set signals TSET<0:3>, and enables any one 10 among the first to fourth test set signals TSET<0:3>by decoding two address bits ADD<M-1:M> of the address ADD<1: M>. Here, the first test set signal TSET<0> is inputted to a (4P+1)<sup>th</sup> data control unit 203\_4P+1 among the N data control units 203\_1 to 203\_N, and the second test set signal 15 TSET<1> is inputted to a  $(4P+2)^{th}$  data control unit 203\_4P+2 among the N data control units 203\_1 to 203\_N. The third test set signal TSET<2> is inputted to a  $(4P_{\perp}3)^{th}$ data control unit 203\_4P+3 among the N data control units 203\_1 to 203\_N, and the fourth test set signal TSET<3> is inputted to a  $(4P_{+}4)^{th}$  data control unit 203\_4P+4 among the N data control units 203\_1 to 203\_N. For illustration purposes, it is assumed that two address bits ADD<M-1:M> having a value of '00' are inputted to the test set signal <sub>25</sub> generation unit 201B and the test set signal generation unit 201B generates a test set signal TSET<0:3> having a value of '1000'.

The (4P+1)<sup>th</sup> data control unit 203\_4P+1 performs a control operation to store a write data of a logic low level in a <sup>30</sup> (4P<sub>+</sub>1)<sup>th</sup> page buffer 100\_4P+1 which corresponds to the (4P+1)<sup>th</sup> data control unit 203\_4P+1 in response to a first test set signal TSET<0> of a logic high level. In short, the write data of a logic low level is loaded on the latch node QC of the (4P+1)<sup>th</sup> page buffer 100\_4P+1.

Meanwhile, since a second test set signal TSET<1> of a logic low level is inputted to the  $(4P+2)^{th}$  data control unit  $203\_4P+2$ , the  $(4P+2)^{th}$  data control unit  $203\_4P+2$  does not change the level of the write data that is stored in the  $(4P+2)^{th}$  40 page buffer  $100\_4P+2$ . In short, the write data loaded on the latch node QC of the  $(4P+2)^{th}$  page buffer  $100\_4P+2$  maintains a logic high level.

Since a third test set signal TSET<2> of a logic low level is inputted to the  $(4P+3)^{th}$  data control unit  $203\_4P+3$ , the  $(4P+3)^{th}$  data control unit  $203\_4P+3$  does not change the level of the write data. In short, the write data loaded on the latch node QC of the  $(4P+3)^{th}$  page buffer  $100\_4P+3$  maintains a logic high level.

Since a fourth test set signal TSET<3> of a logic low level is inputted to the  $(4P+4)^{th}$  data control unit  $203\_4P+4$ , the  $(4P+4)^{th}$  data control unit  $203\_4P+4$  does not change the level of the write data. In short, the write data loaded on the latch node QC of the  $(4P+4)^{th}$  page buffer  $100\_4P+4$  maintains a logic high level.

Thus, the pattern of the write data that are stored in the N page buffers 100\_1 to 100\_N becomes '0111 0111 0111...'. The write data stored in the N page buffers 100\_1 to 100\_N, which are '0111 0111 0111...', are transferred to N memory cells through the N bit lines BL1 to BLN and programmed in the N memory cells.

Thus, the pattern of the write data that are stored in the N page buffers 100\_1 to 100\_N illustrated in FIG. 4 in the test 65 mode, which means that the test signal TM\_BIT is in a logic high level is as shown in Table 3.

Pattern example of write data that may be generated by decoding two address bits ADD< M-1:M>

ADD <m-1:m></m-1:m>	TSET<0:3>	Pattern of Write Data
00	1000	0111 0111 0111 0111
01 10	0100 0010	1011 1011 1011 1011 1101 1101 1101
11	0001	1110 1110 1110 1110

In reference to FIG. 2, an exemplary embodiment of the present invention controls the write data stored in the oddnumbered page buffers 100\_2K-1 and the write data stored in the even-numbered page buffers 100\_2K to have a different value by using one address bit ADD<M> of the address ADD<1:M>. In reference to FIG. 4, another exemplary embodiment of the present invention controls the write data stored in one page buffer and the write data stored in the other page buffers among four page buffers to have a different logic value by using two address bits ADD<M-1:M> of the address ADD<1:M>. However, the exemplary embodiments are exemplary only, and a non-volatile memory device in accordance with an embodiment of the present invention may generate write data of different patterns to be stored in N page buffers 100\_1 to 100\_N by using different portions of the bits of an address ADD<1:M>. For example, as shown in the following Table 4, write data of different patterns may be generated by using three address bits ADD<M-2:M> of the address ADD<1:M> and stored in N page buffers 100\_1 to 100\_N.

TABLE 4

	-	le of write data that are generated hree address bits ADD <m-2:m></m-2:m>
ADD <m-2< th=""><th>:M&gt;</th><th>Pattern of Write Data</th></m-2<>	:M>	Pattern of Write Data
	000	01 01 01 01 01 01 01
	001	10 10 10 10 10 10 10
	010	110 110 110 110 110 110
	011	101 101 101 101 101
	100	1001 1001 1001 1001 1001
	101	1011 1011 1011 1011 1011
	110	1101 1101 1101 1101 1101
	111	1111 1111 1111 1111 1111

According to an embodiment of the present invention, since write data of diverse patterns may be generated within a non-volatile memory device by using a portion of the bits of an address ADD<1:M> and programmed in memory cells (not shown), a test operation of the non-volatile memory device may be performed within a short time by using test data of diverse patterns. Therefore, the test time for a non-volatile memory device may be reduced.

While the present invention has been described with respect to the specific embodiments, it will be apparent to those skilled in the art that various changes and modifications may be made without departing from the spirit and scope of the invention as defined in the following claims.

What is claimed is:

- 1. A non-volatile memory device, comprising:
- a plurality of bit lines;
- a plurality of page buffers corresponding to the bit lines, respectively, and configured to each store a write data; and
- a control circuit configured to control at least one page buffer of the plurality of page buffers to store the write

data of a first logic level and control other ones of the plurality of page buffers to store the write data of a second logic level, wherein the control circuit is further configured to select the at least one page buffer based on an address inputted to the control circuit,

wherein the control circuit controls the write data stored in odd-numbered page buffers among the plurality of page buffers and the write data stored in even-numbered page buffers among the plurality of page buffers to have a different value by using one address bit of the address.

- 2. The non-volatile memory device of claim 1, wherein the control circuit comprises:
  - a test set signal generation unit configured to generate a plurality of test set signals and activate at least one of the test set signals by decoding the address in a test mode; and
  - a plurality of data control units corresponding to the plurality of page buffers, respectively, and configured to each control the corresponding page buffer to store the write data of the first logic level when a test set signal inputted to the data control unit is activated and each control the corresponding page buffer to store the write data of the second logic level when a reset signal is activated.
- 3. The non-volatile memory device of claim 2, wherein the reset signal is commonly input to the data control units.
- 4. The non-volatile memory device of claim 1, wherein the first logic level is a logic low level and the second logic level is a logic high level.
- 5. The non-volatile memory device of claim 2, wherein the test set signal generation unit is configured to deactivate the test set signals in a normal mode of the non-volatile memory device.
- 6. The non-volatile memory device of claim 2, wherein the reset signal is a signal activated during an initial period of a

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test operation, and the control circuit is configured to activate at least one of the test set signals after the initial period of the test operation.

- 7. The non-volatile memory device of claim 1, wherein the control circuit comprises:
  - a test set signal generation unit configured to generate a plurality of test set signals and activate at least one of the test set signals by decoding the address in a test mode; and
  - a plurality of data control units corresponding to the plurality of page buffers, respectively, and configured to each control the corresponding page buffer to store the write data of the first logic level when any one of a test set signal inputted to the data control unit and a set signal inputted to the data control unit is activated and each control the corresponding page buffer to store the write data of the second logic level when a reset signal is activated.
  - **8**. A non-volatile memory device, comprising: a plurality of bit lines;
  - a plurality of page buffers corresponding to the plurality of bit lines, respectively, and configured to each store a write data; and
  - a control circuit configured to control at least one page buffer of the plurality of page buffers to store the write data of a first logic level and control other ones of the plurality of page buffers to store the write data of a second logic level, wherein the control circuit is further configured to select the at least one page buffer based on a portion of bits of an address consisting of multiple bits,
  - wherein the write data of different patterns to be stored in the plurality of page buffers by using different portions of the bits of the address are generated.

\* \* \* \*